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# TECHNICAL REPORT



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**Roadmap of optical circuit boards and their related packaging technologies**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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THEIR RELATED PACKAGING TECHNOLOGIES**
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The text of this technical report is based on the following documents:

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Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

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## **ROADMAP OF OPTICAL CIRCUIT BOARDS AND THEIR RELATED PACKAGING TECHNOLOGIES**

### **1 Scope**

This Technical Report covers the roadmap of optical circuit boards, and its related packaging technologies including optical circuit board connectors and optical modules on boards.